

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPD50N08S4-13	**Issued**	08. April 2022
MA#	MA005710994		
Package	PG-TO252-3-313	**Weight***	318.48 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.872	0.59	0.59	5878	5878
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		139	
	non noble metal	iron	7439-89-6	0.147	0.05		462	
	non noble metal	copper	7440-50-8	147.096	46.19	46.25	461865	462466
wire	non noble metal	aluminium	7429-90-5	2.896	0.91	0.91	9094	9094
encapsulation	inorganic material	zincoxide	1314-13-2	1.402	0.44		4402	
	miscellaneous	miscellaneous	-	7.010	2.20		22012	
	plastics	epoxy resin	-	21.031	6.60		66036	
	inorganic material	silicondioxide	60676-86-0	110.764	34.78	44.02	347787	440237
leadfinish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11743	11743
plating	inorganic material	phosphorus	7723-14-0	0.003			11	
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4460	4471
solder	non noble metal	tin	7440-31-5	0.037	0.01		116	
	noble metal	silver	7440-22-4	0.046	0.01		145	
	non noble metal	lead	7439-92-1	1.770	0.56	0.58	5557	5818
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	6.02	6.03	60215	60293
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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